This Sheet Has Been Replaced

LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND STRUCTURE THEREOF

ABSTRACT

An electronic package assembly where a low profile integrated circuit chip package (13) is soldered to an organic (e.g., epoxy resin) substrate (11), e.g., a printed circuit board or card, the projecting conductive leads (21) of the integrated circuit chip package (13) and the solder which substantially covers these leads (21) (and respective conductors on the substrate) having been substantially covered with ultraviolet photocured encapsulant material (e.g., polymer resin) to provide reinforcement for the solder-lead connections. The encapsulant material is dispensed about the solder and lead joints following solder reflow and solidification so as to substantially surround the solder and any portions of the leads not covered with solder.

Fig. 1.